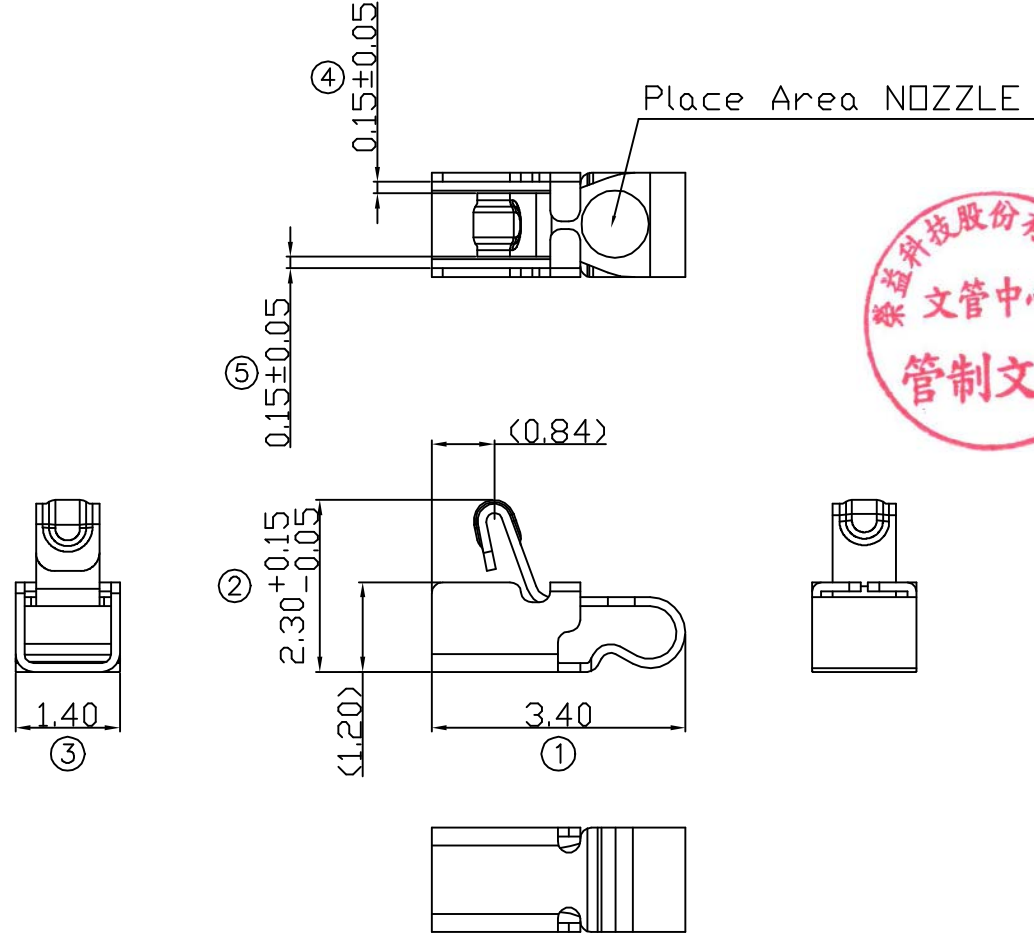
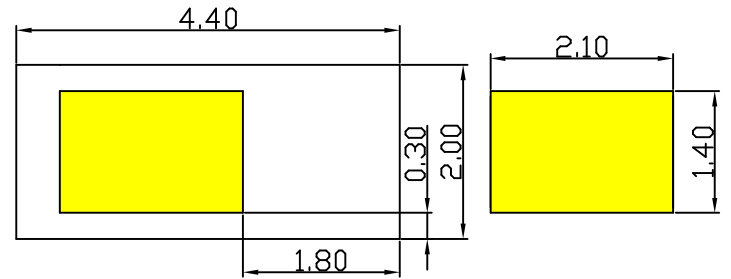


A  
B  
C  
D  
E  
F

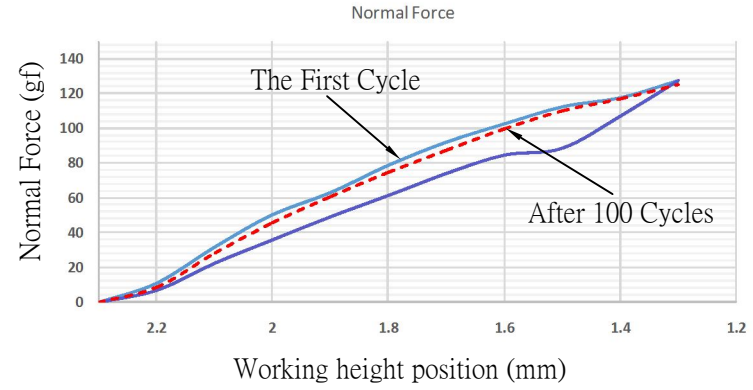


Place Area NOZZLE

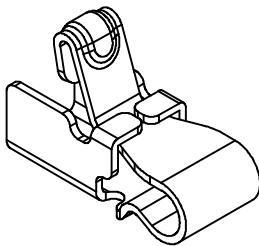


RECOMMENDED SOLDERING PCB LAYOUT

TOLERANCE(.XX±0.05)



- Note:
1. Material: Copper Alloy Thickness 0.12mm
  2. Electroplate:
    - Gold Flash on contact area
    - Gold Flash on solder area
    - Nickel underplating over all
  3. Electrical Characteristics:
    - 3-1 Current Voltage: 12V
    - 3-2 Current Rate: 3A
    - 3-3 Contact Resistance: Normal Compression <math><30m\Omega</math>
  4. Working Height of Application: 1.30~1.90 mm
  5. Spring Force Tolerance is  $\pm 20gf$
  6. Operating Temperature:  $-20^{\circ}C \sim +85^{\circ}C$



00	05/04-'16	Design creation						
REV	Date	Description						
DRAFT	Hardy Hsieh	DATE	05/04-'16	RoHS Compatible				
CHECKER	Justin Wu	DATE	05/04-'16					
APPROVAL	Jacky Lin	DATE	05/04-'16					
		SHEET	1-2	SCALE	Not to scale	UNIT	mm	

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<- ≤120	±0.15	0.20	0.30
120<- ≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		

**EMI STOP CORP.**  
EMI STOP  
EMISTOP QTT-23G CUS P/N